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(12) **United States Design Patent** (10) **Patent No.:** **US D982,561 S**
Lin (45) **Date of Patent:** **** Apr. 4, 2023**

(54) **EARPHONE**
(71) Applicant: **Shenzhen Shengling Technology Co., Ltd, Shenzhen (CN)**
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(**) Term: **15 Years**
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(51) **LOC (14) Cl.** **14-01**
(52) **U.S. Cl.**
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CPC H04R 1/10; H04R 25/00; H04R 1/1066;
H04R 1/1016; H04R 5/033; H04R
5/0335; H04R 1/1083; H04R 1/105;
H04R 1/02; H04R 1/1091
See application file for complete search history.

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(57) **CLAIM**

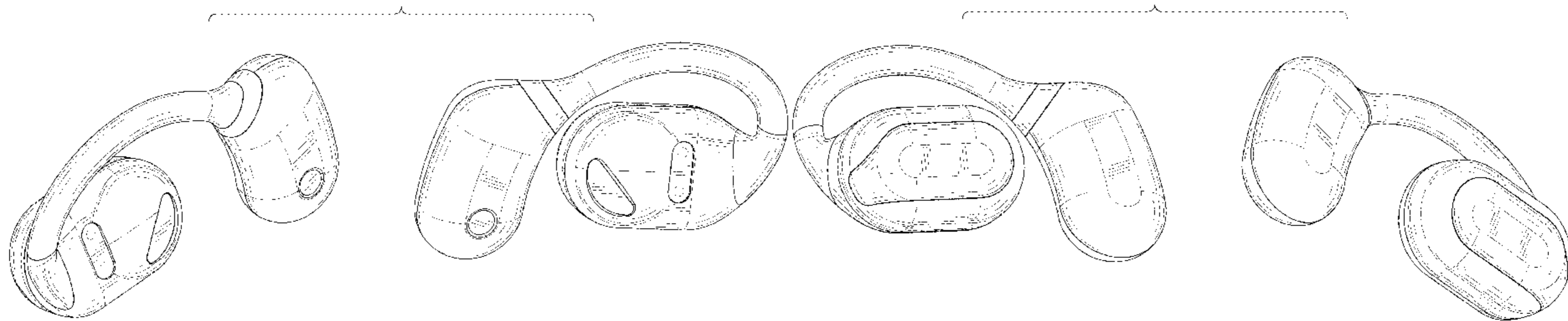
The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an earphone showing my new design;
FIG. 2 is another perspective view thereof;
FIG. 3 is a front elevational view thereof;
FIG. 4 is a rear elevational view thereof;
FIG. 5 is a left side elevational view thereof;
FIG. 6 is a right side elevational view thereof;
FIG. 7 is a top plan view thereof;
FIG. 8 is a bottom plan view thereof; and,
FIG. 9 is a perspective view of the earphone where the earphone is received in the charging case.
The dash-dash broken lines in the drawings depict portions of the earphone that form no part of the claimed design.

1 Claim, 9 Drawing Sheets

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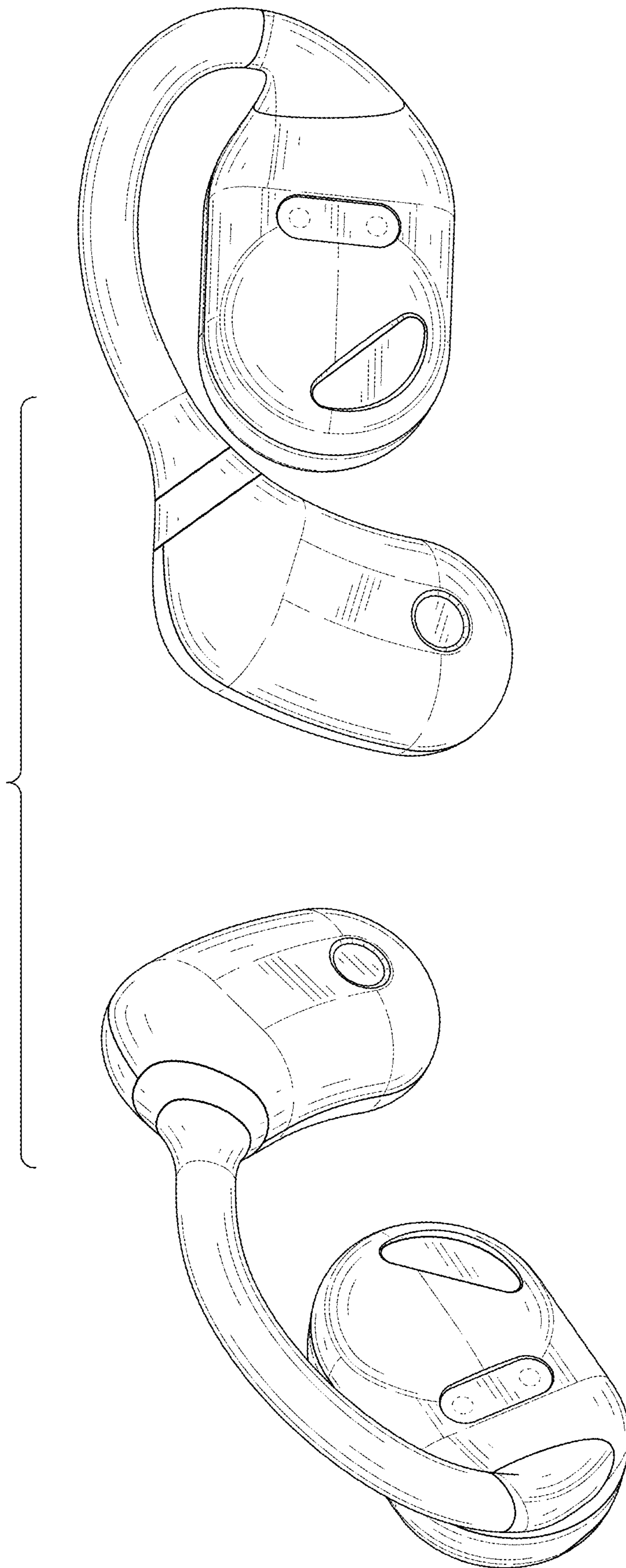


FIG. 1

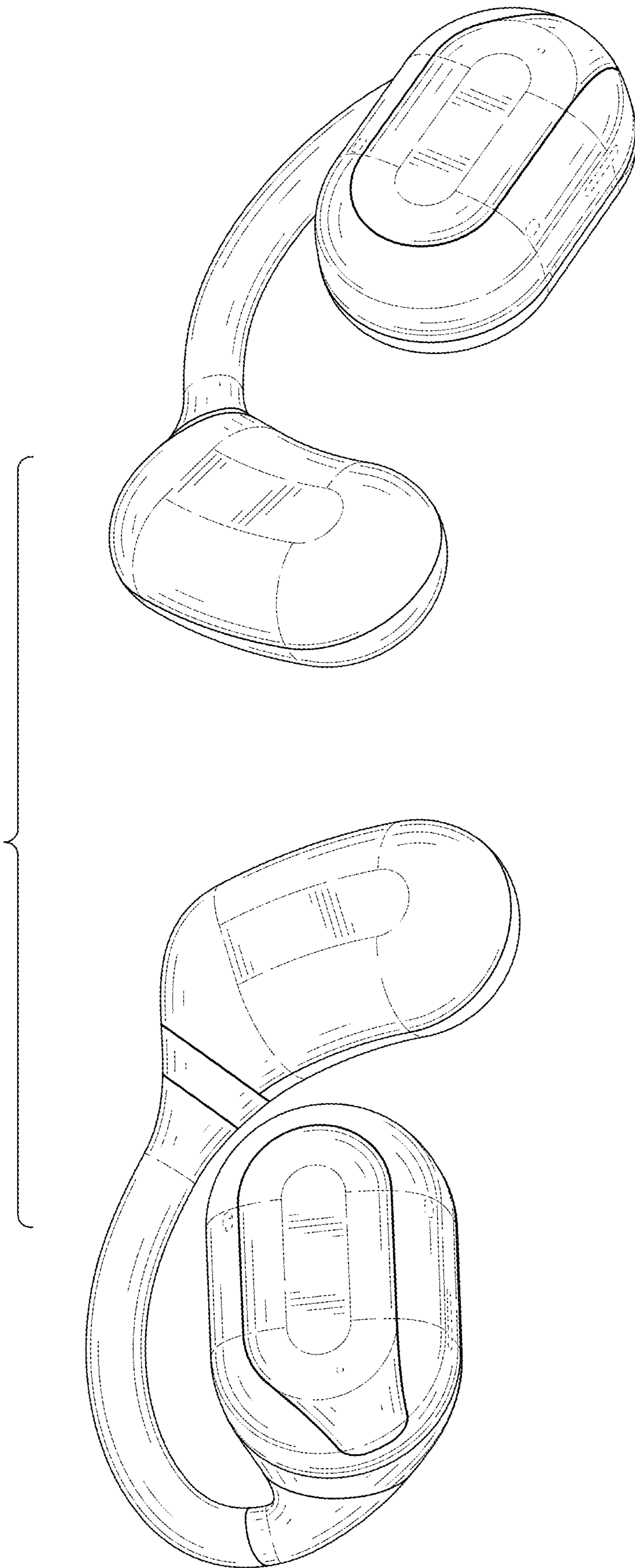


FIG. 2

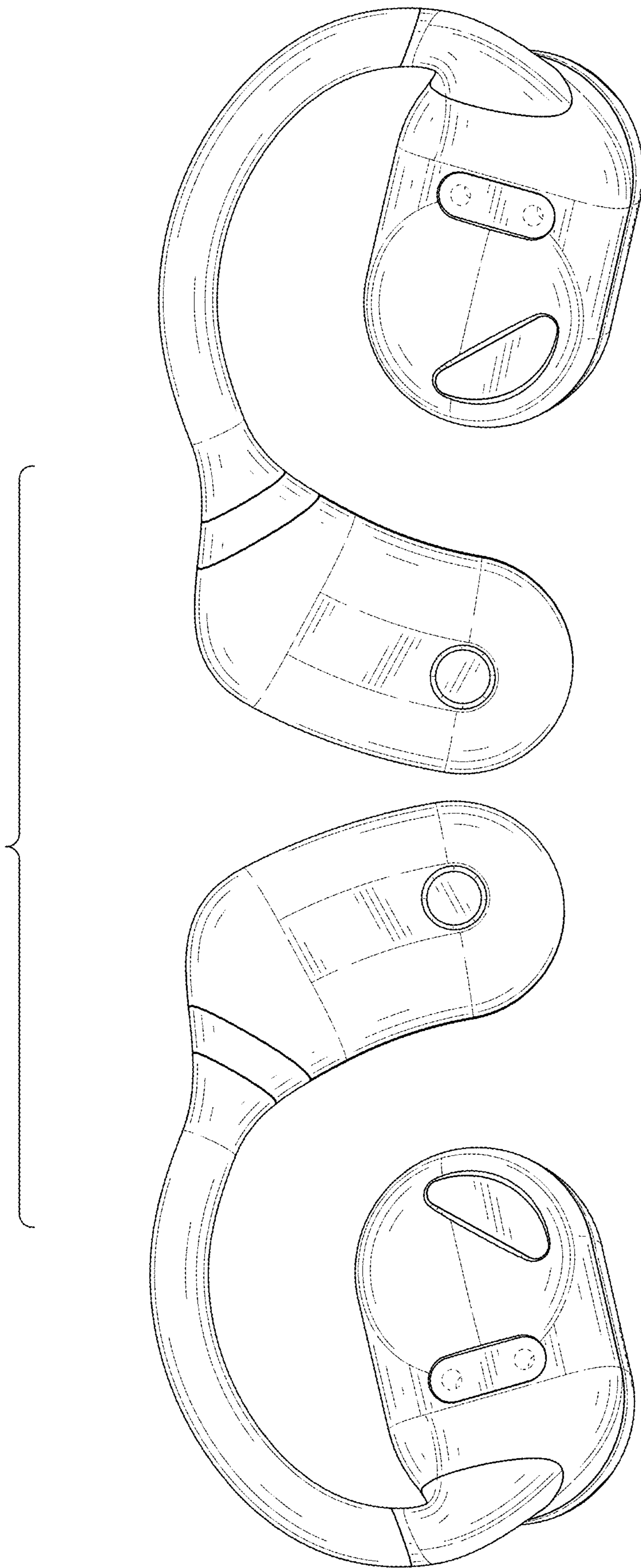


FIG. 3

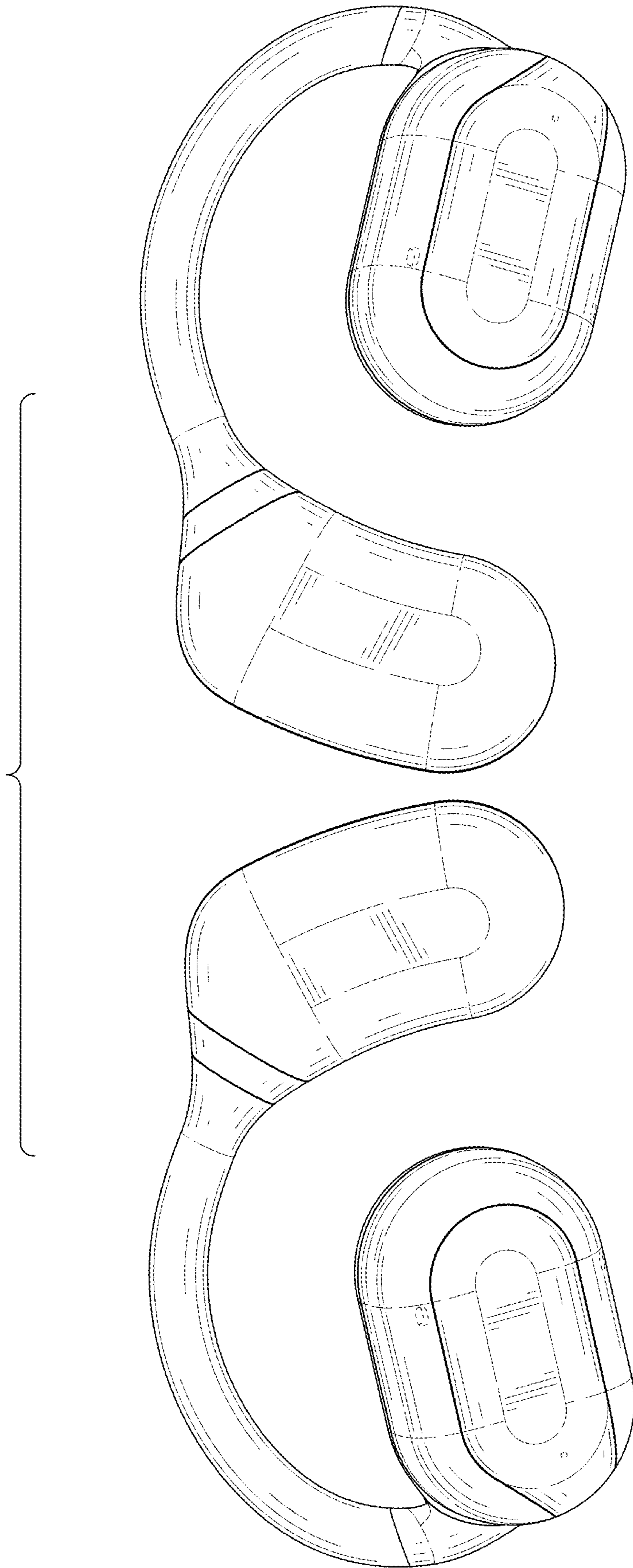


FIG. 4

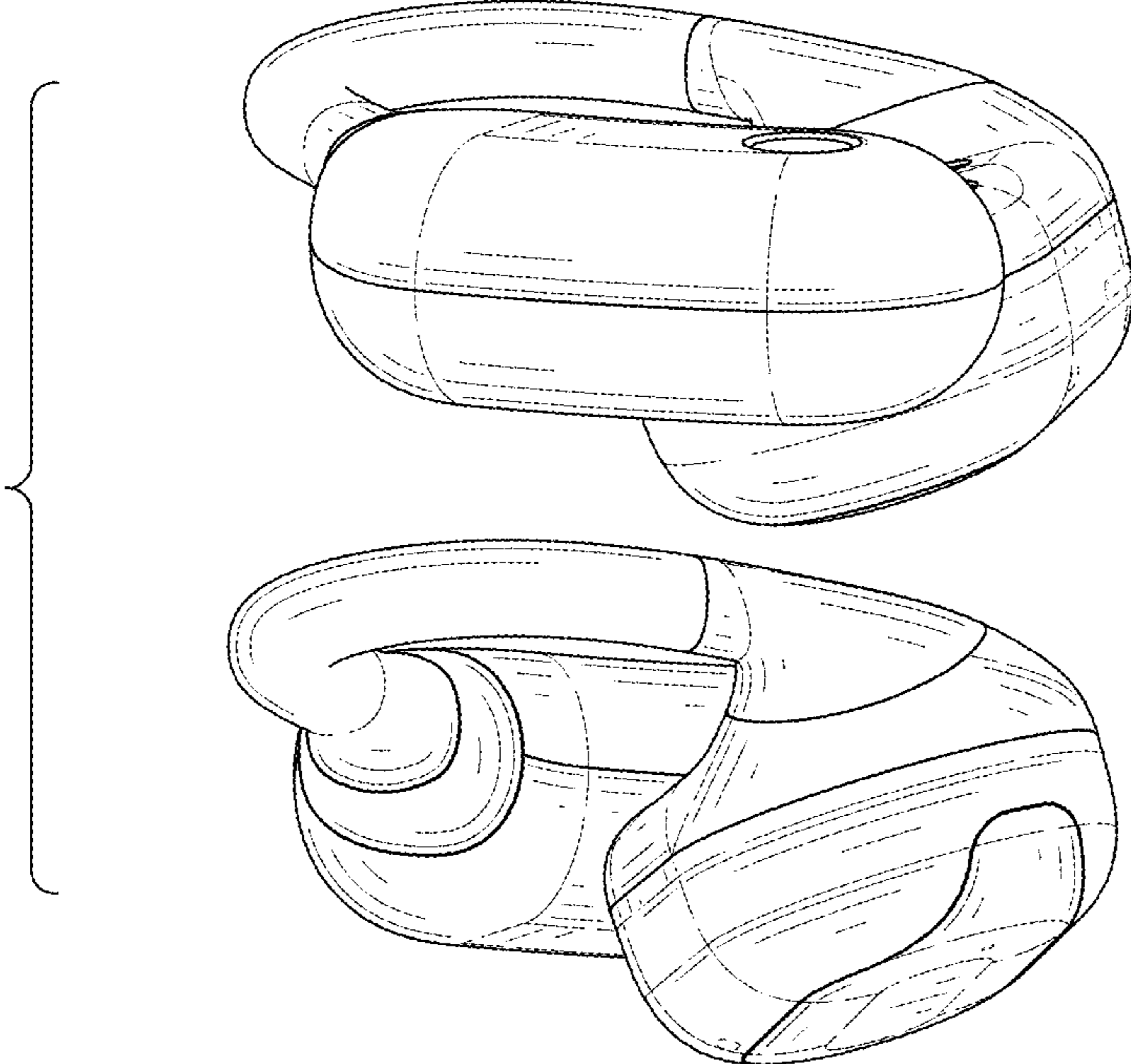


FIG. 5

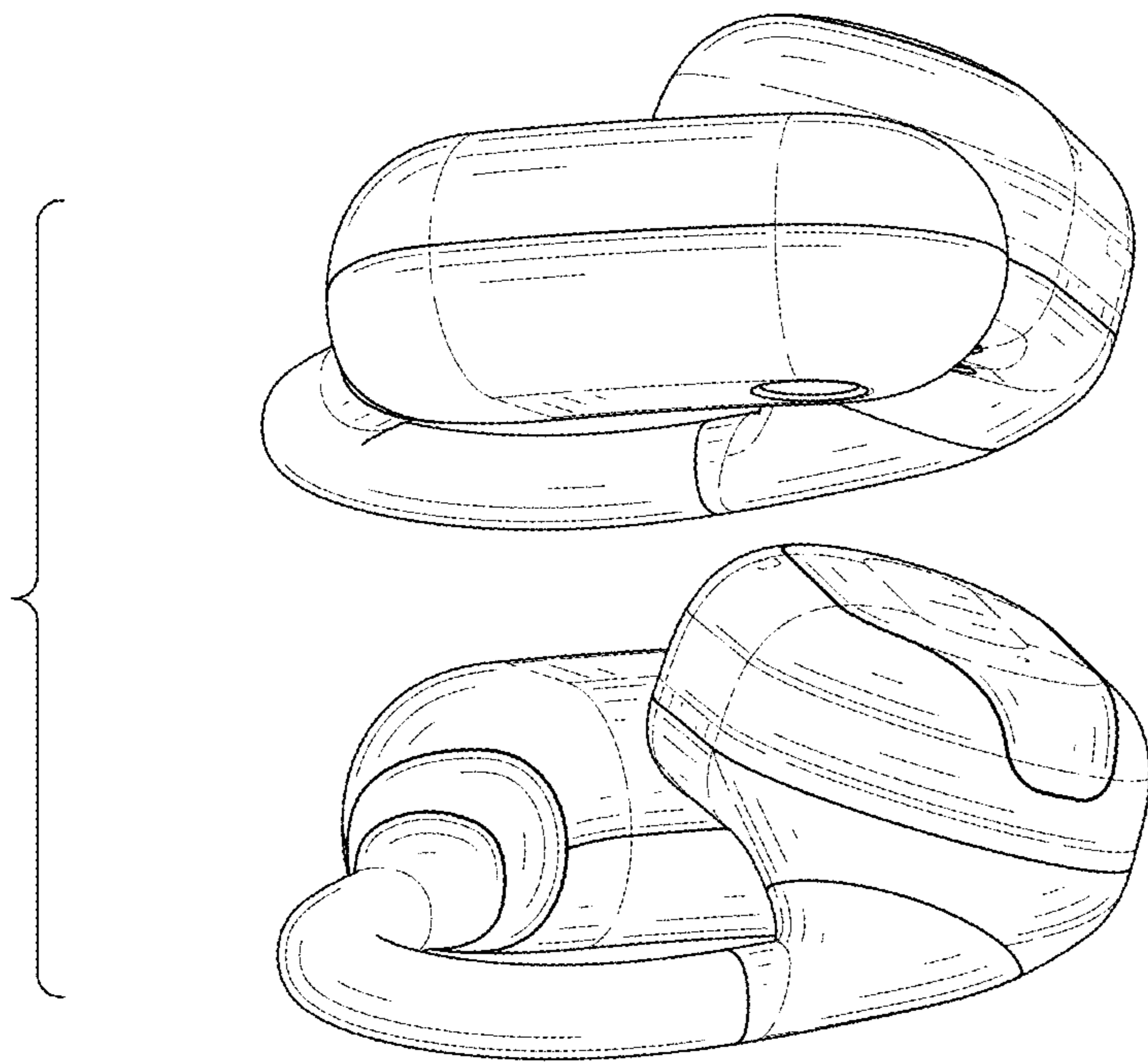


FIG. 6

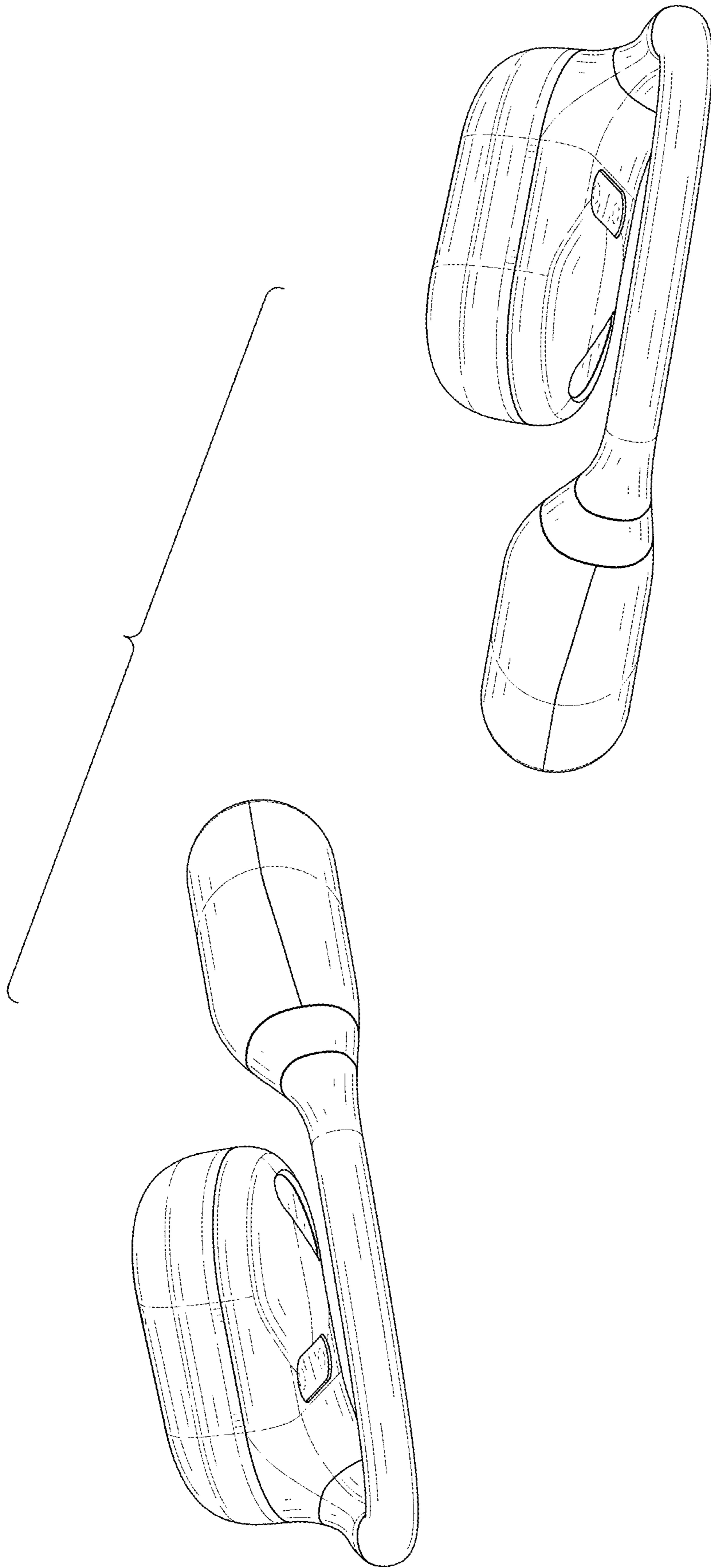


FIG. 7

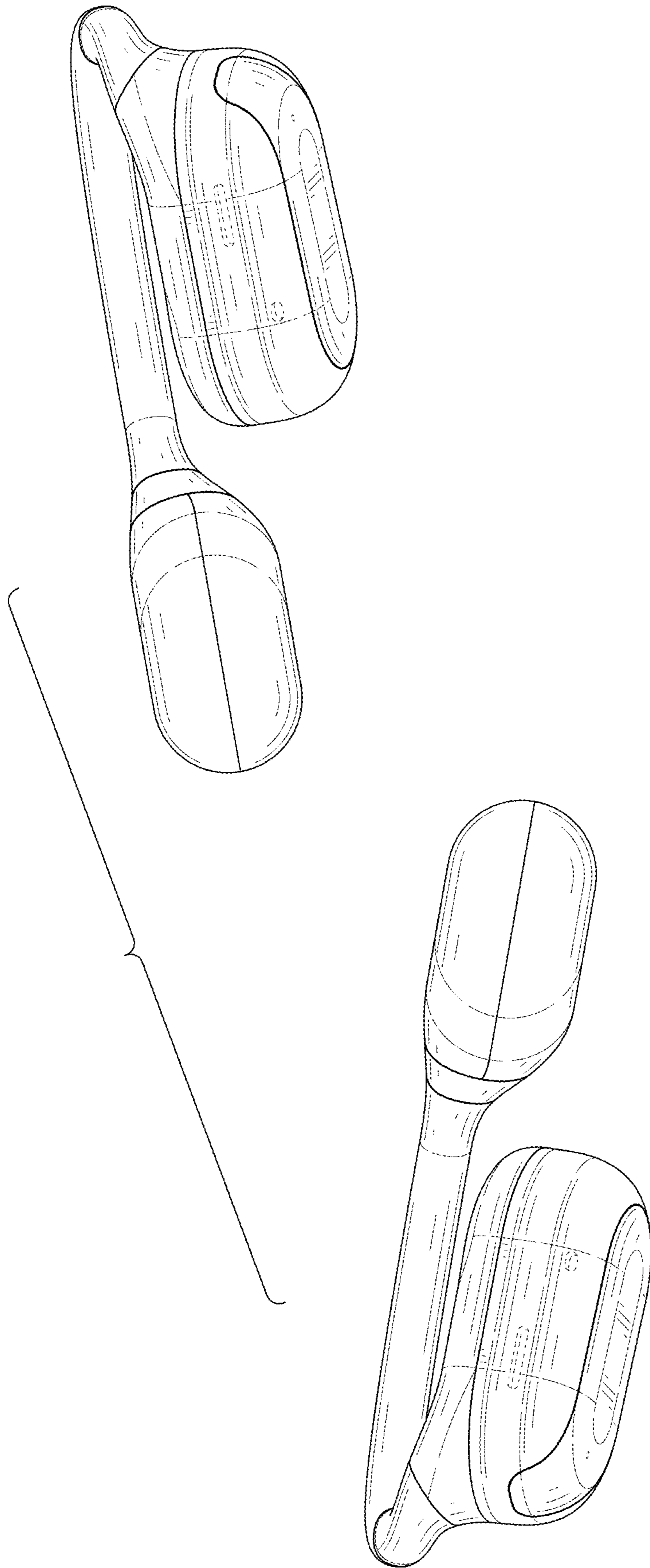


FIG. 8

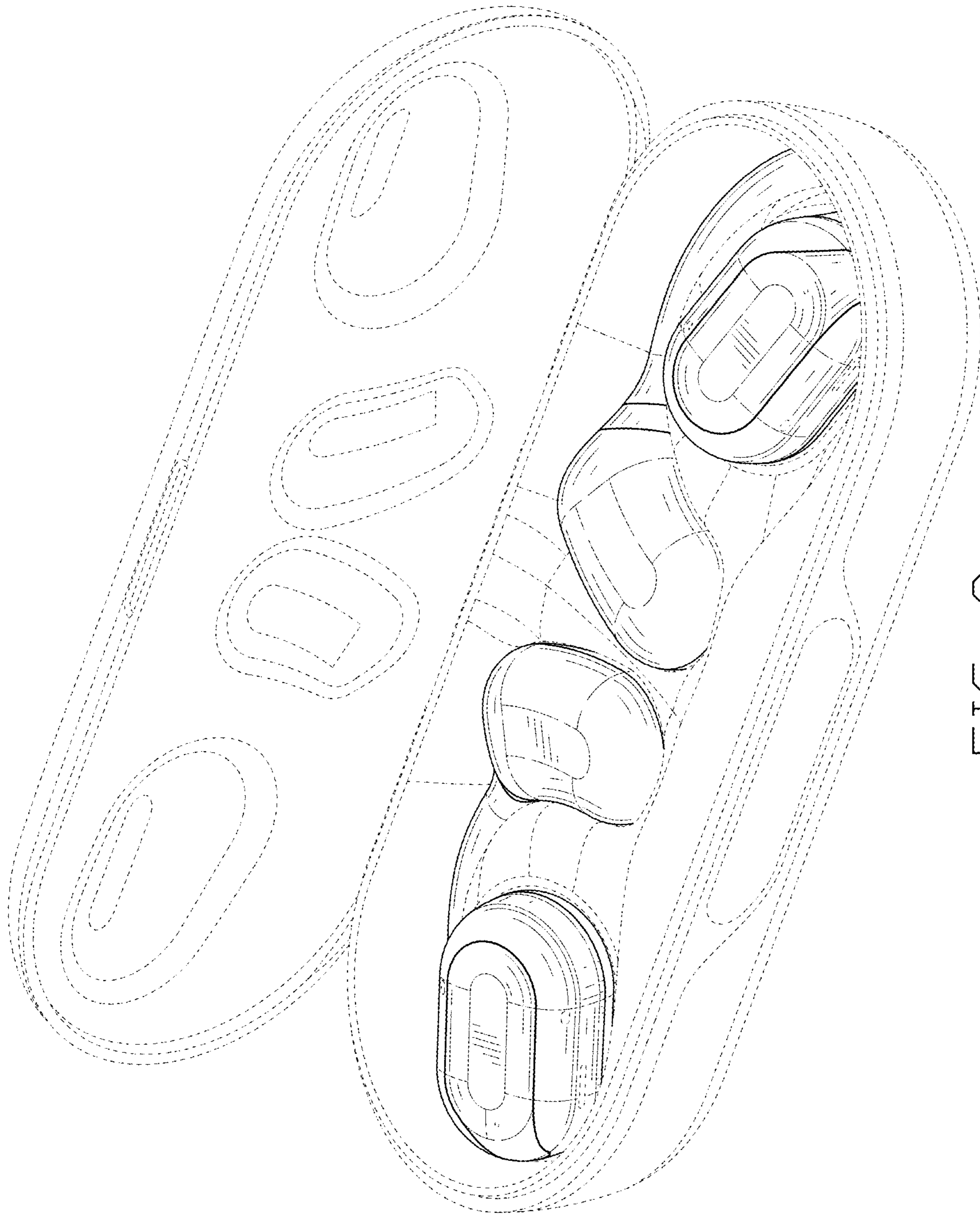


FIG. 9